Nch 60V 80A Power MOSFET

V _{DSS}	60V
R _{DS(on)} (Max.)	7.0mΩ
I _D	±80A
P_D	96W

● Features

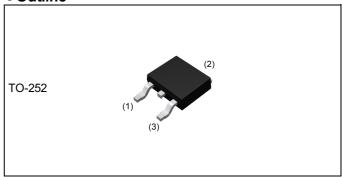
- 1) Low on resistance
- 2) High power small mold package
- 3) Pb-free lead plating; RoHS compliant
- 4) 100% Rg and UIS tested
- 5) Halogen free

Application

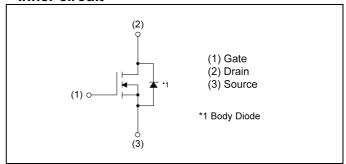
Switching

Power tool

Outline



●Inner circuit



Packaging specifications

	Packing	Embossed Tape
Туре	Basic ordering unit (pcs)	2500
	Taping code	TL
	Marking	RD3L08CGN

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	60	V
Continuous drain current	Continuous drain current V _{GS} = 10V		±80	Α
Pulsed drain current	I _{DP} *2	±160	Α	
Gate - Source voltage	V_{GSS}	±20	V	
Avalanche current, single pulse	I _{AS} *3	37	Α	
Avalanche energy, single pulse	E _{AS} *3	52	mJ	
Power dissipation	P _D *1	96	W	
Junction temperature	T _j	150	°C	
Operating junction and storage temper	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Lleit
Faranieter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	1	ı	1.3	°C/W

● Electrical characteristics (T_a = 25°C)

Daramatar	Cymah al	Conditions	Values			l limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		60	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j} I_D = 1 \text{mA}$ referenced to 25°C		-	60	-	mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V	-	-	10	μA
Gate - Source leakage current	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 50\mu A$	1.0	-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-5.6	-	mV/°C
Static drain - source	R _{DS(on)} *4	V _{GS} = 10V, I _D = 80A	-	5.3	7.0	0
on - state resistance		V _{GS} = 4.5V, I _D = 40A	-	7.4	10.7	mΩ
Gate resistance	R _G f = 1MHz, open drain		-	1.8	-	Ω
Forward Transfer Admittance	Y _{fs}	V _{DS} = 5V, I _D = 40A	24	-	-	S

^{*1} Tc=25°C, Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s , Duty cycle \leq 1%

^{*3} L \simeq 0.05mH, V_{DD} = 30V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

Darameter	Cumbal	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	2600	-	
Output capacitance	C _{oss}	V _{DS} = 30V	-	510	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	130	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 30V, V_{GS} = 10V$	1	17	1	
Rise time	t _r *4	I _D = 40A	1	32	ı	no
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 0.75\Omega$		71		ns
Fall time	t _f *4	R _G = 10Ω	-	34	-	

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Conditions		Values			1.1:4
Parameter	Symbol			Min.	Тур.	Max.	Unit
T. I.		V _{GS} = 10V	-	55	-		
Total gate charge	Q _g *4	$V_{DD} \simeq 30V$		-	27	-	
Gate - Source charge	Q _{gs} *4	I _D = 40A	V _{GS} = 4.5V	-	11	-	nC
Gate - Drain charge	Q _{gd} *4			-	9.8	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
raiametei	Symbol	ol Conditions		Тур.	Max.	Offic
Continuous forward current	I _S	T = 25°C	-	-	80	Α
Pulse forward current	I _{SP} *2	T _a = 25°C	-	-	160	Α
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 80A	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 50A, V _{GS} =0V	-	42	-	ns
Reverse recovery charge	Q _{rr}	di/dt = 100A/μs	-	53	-	nC

Fig.1 Power Dissipation Derating Curve

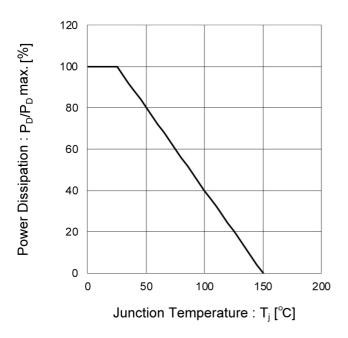
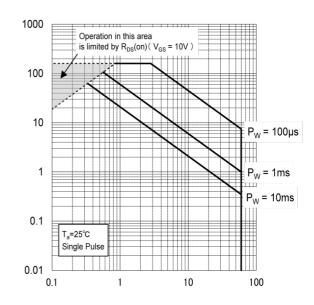


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

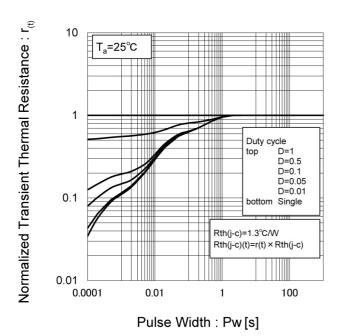
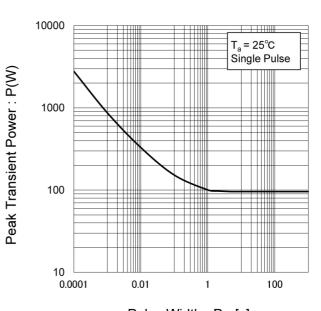
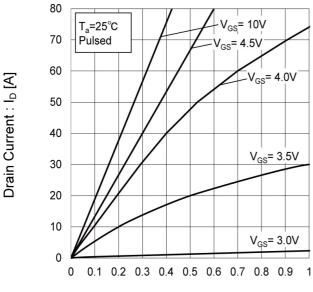


Fig.4 Single Pulse Maximum Power dissipation



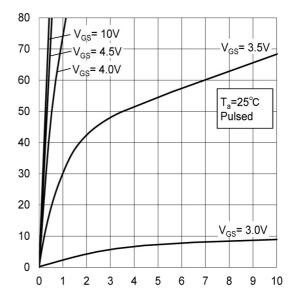
Pulse Width : Pw [s]

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

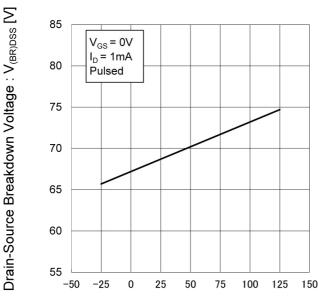
Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs. **Junction Temperature**



Junction Temperature : T_i [°C]

Fig.8 Typical Transfer Characteristics

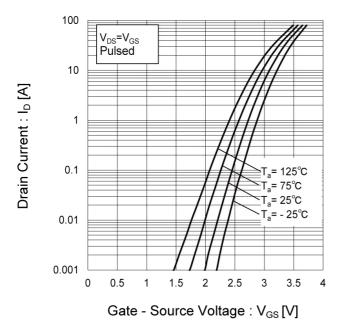


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

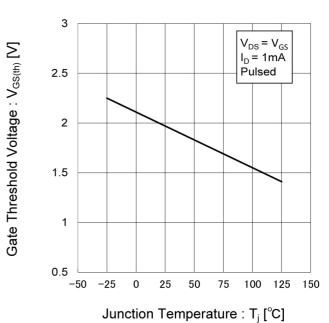


Fig.10 Forward Transfer Admittance vs.
Drain Current

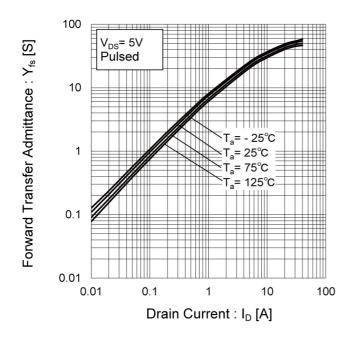
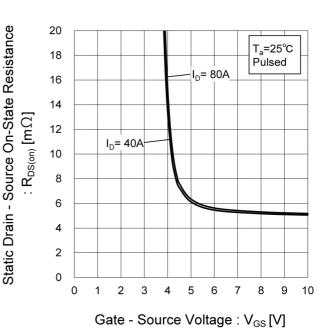


Fig.11 Drain Current Derating Curve

120 Drain Current Dissipation: I_D/I_Dmax. [%] 100 80 60 40 20 0 50 75 150 0 25 100 125 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



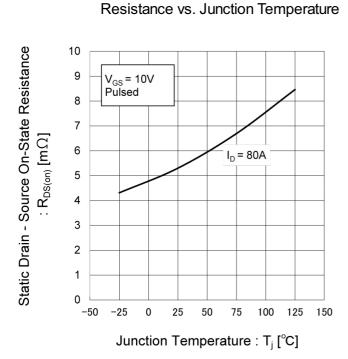


Fig.13 Static Drain - Source On - State

ROHM

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

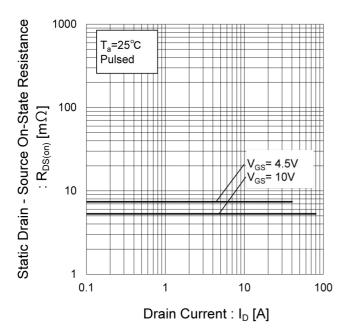


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

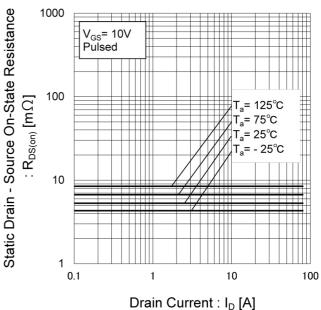


Fig.16 Static Drain - Source On - State
Resistance vs. Drain Current (III)

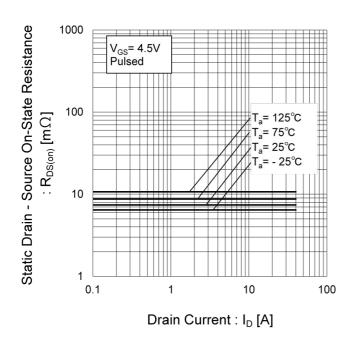
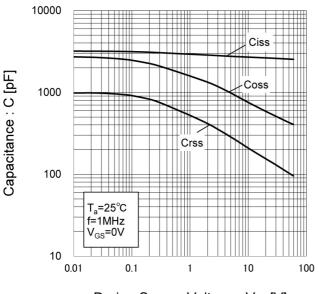


Fig.17 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage: V_{DS} [V]

Fig.18 Switching Characteristics

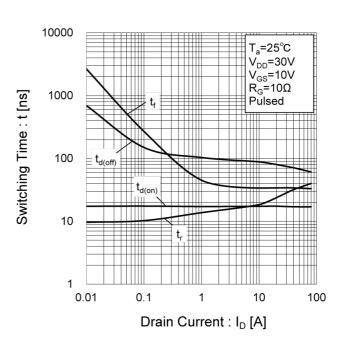
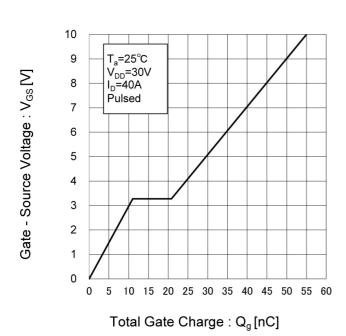


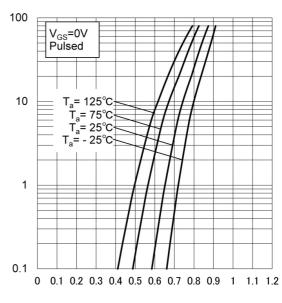
Fig.19 Dynamic Input Characteristics



Source Current :I_S [A]

Fig.20 Source Current vs.

Source Drain Voltage



Source-Drain Voltage: V_{SD}[V]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

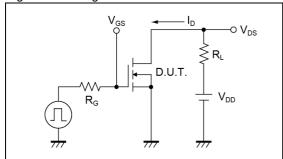


Fig.2-1 Gate Charge Measurement Circuit

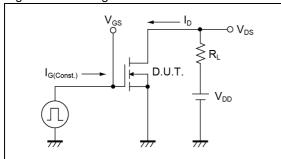


Fig.3-1 Avalanche Measurement Circuit

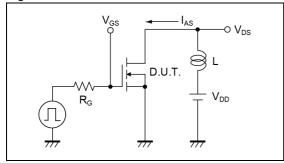


Fig.1-2 Switching Waveforms

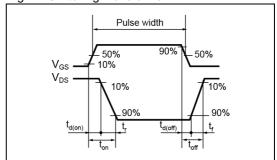


Fig.2-2 Gate Charge Waveform

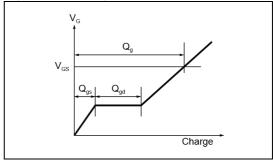
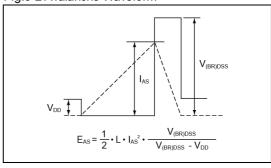
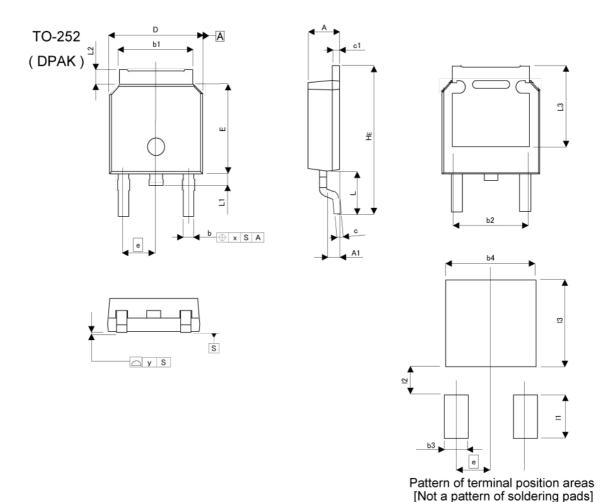


Fig.3-2 Avalanche Waveform



Dimensions



MILIMETERS **INCHES** DIM MIN MIN MAX MAX Α 2.10 2.30 0.083 0.091 A1 0.70 1.10 0.028 0.043 b 0.65 0.85 0.026 0.033 b1 5.10 5.40 0.201 0.213 5.10 0.201 b2 0.016 0.40 0.60 0.024 С c1 0.40 0.60 0.016 0.024 D 6.40 6.80 0.252 0.268 0.091 е Ε 6.00 6.40 0.236 0.252 HE 10.50 0.374 0.413 9.50 L 0.114 0.70 L1 0.90 0.028 0.035 L2 0.70 1.30 0.028 0.051 L3 5.30 0.209 0.10 0.004 0.10 0.004

DIM	MILIME	ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
b3	2	1.10	-	0.043
b4	-	5.40	-	0.213
l1	0.	90	0.0	035
12	2.00		0.079	
13	5.	30	0.3	209

Dimension in mm/inches



Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CI ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.003



RD3L08CGN - Web Page

Part Number	RD3L08CGN
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes